Product name:
Printed Circuit Board Peel Strength and Solderability Test System

Product code:
CMI-IND-0439



Description

Bench system combining a 90 degree peel fixture for copper foil adhesion and a solder pot for wetting checks on pads and leads. Used by PCB fabricators and electronics assembly quality laboratories.

Technical specification

Dip time	0 to 30 s
Accuracy	+/- 0.5 percent
Standards	IPC-TM-650 2.4.8, IEC 61189-3, J-STD-003
Power	230 V AC, 50 Hz

Standard Accessories

- Peel fixture
- Solder pot
- Flux bottle

Copper strips on laminate are peeled at 90 degrees on a small tensile frame and a separate solder bath checks wetting time of pads and leads. Both tests qualify boards before assembly.

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Features

- 90 degree peel fixture with strain gage
- Digital force gauge with peak hold
- Lead-free solder pot to 300 deg C
- Timer with dip speed control
- Specimen cutter for 3 mm strips

Technical Specifications

Peel capacity	100 N
Peel speed	50 mm/min
Solder pot temperature	Ambient to 300 deg C
Dip depth	0 to 20 mm